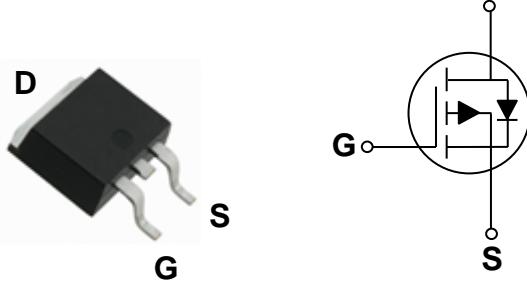


### General Description

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### TO252 Pin Configuration



BVDSS	RDS(ON)	ID
-60V	9.2mΩ	-70A

### Features

- -60V, -70A, RDS(ON) = 9.2mΩ@VGS = -10V
- Fast switching
- Green Device Available
- Suit for -4.5V Gate Drive Applications

### Applications

- POL Applications
- Load Switch
- LED Application



### Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	-60	V
V <sub>Gs</sub>	Gate-Source Voltage	$\pm 20$	V
I <sub>D</sub>	Drain Current – Continuous ( $T_c=25^\circ\text{C}$ )	-70	A
	Drain Current – Continuous ( $T_c=100^\circ\text{C}$ )	-44.3	A
I <sub>DM</sub>	Drain Current – Pulsed <sup>1</sup>	-280	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	320	mJ
IAS	Single Pulse Avalanche Current <sup>2</sup>	80	A
P <sub>D</sub>	Power Dissipation ( $T_c=25^\circ\text{C}$ )	133	W
	Power Dissipation – Derate above $25^\circ\text{C}$	1.06	W/ $^\circ\text{C}$
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJC</sub>	Thermal Resistance Junction to Case	---	0.94	$^\circ\text{C}/\text{W}$
R <sub>θJA</sub>	Thermal Resistance Junction to Ambient	---	62	$^\circ\text{C}/\text{W}$

## Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)

### Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=-250\mu\text{A}$	-60	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	$\text{BV}_{\text{DSS}}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$	---	0.036	---	$\text{V}/^\circ\text{C}$
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=-60\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	-1	$\mu\text{A}$
		$V_{\text{DS}}=-48\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=125^\circ\text{C}$	---	---	-10	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA

### On Characteristics

$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{\text{GS}}=-10\text{V}$ , $I_D=-20\text{A}$	---	7.6	9.2	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}$ , $I_D=-10\text{A}$	---	9.2	12	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D=-250\mu\text{A}$	-1.2	-1.6	-2.5	V
			---	-6.3	---	$\text{mV}/^\circ\text{C}$
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=-10\text{V}$ , $I_D=-3\text{A}$	---	18	---	S

### Dynamic and switching Characteristics

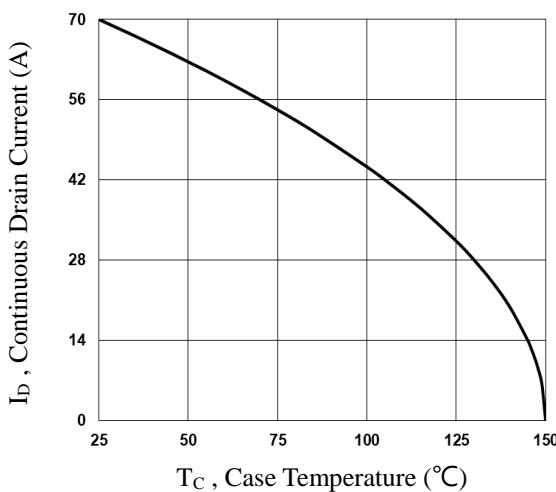
$Q_g$	Total Gate Charge <sup>3, 4</sup>	$V_{\text{DS}}=-48\text{V}$ , $V_{\text{GS}}=-10\text{V}$ , $I_D=-5\text{A}$	---	141	210	nC
$Q_{\text{gs}}$	Gate-Source Charge <sup>3, 4</sup>		---	17	25.5	
$Q_{\text{gd}}$	Gate-Drain Charge <sup>3, 4</sup>		---	28.6	43	
$T_{\text{d(on)}}$	Turn-On Delay Time <sup>3, 4</sup>	$V_{\text{DD}}=-48\text{V}$ , $V_{\text{GS}}=-10\text{V}$ , $R_G=6\Omega$ $I_D=-1\text{A}$	---	70	140	ns
$T_r$	Rise Time <sup>3, 4</sup>		---	205	410	
$T_{\text{d(off)}}$	Turn-Off Delay Time <sup>3, 4</sup>		---	402	804	
$T_f$	Fall Time <sup>3, 4</sup>		---	197	394	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=-25\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $F=1\text{MHz}$	---	8620	12930	pF
$C_{\text{oss}}$	Output Capacitance		---	486	730	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	288	430	

### Drain-Source Diode Characteristics and Maximum Ratings

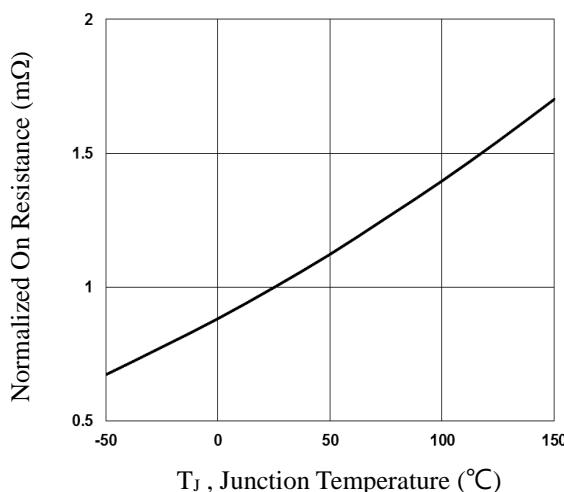
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current	$V_G=V_D=0\text{V}$ , Force Current	---	---	-70	A
$I_{\text{SM}}$	Pulsed Source Current		---	---	-140	A
$V_{\text{SD}}$	Diode Forward Voltage	$V_{\text{GS}}=0\text{V}$ , $I_s=-1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	-1	V

Note :

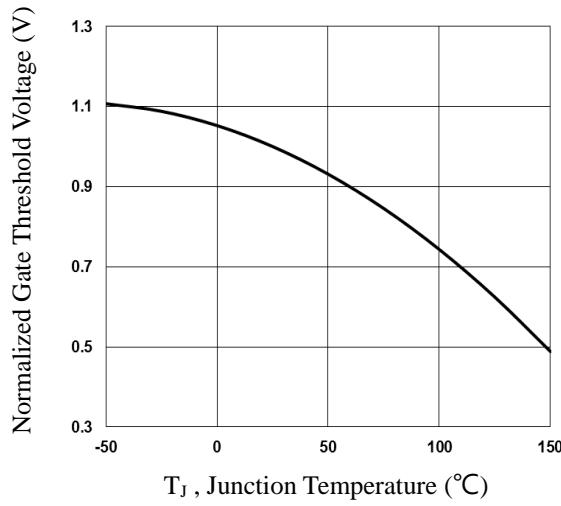
1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2.  $V_{\text{DD}}=50\text{V}$ ,  $V_{\text{GS}}=10\text{V}$ ,  $L=0.1\text{mH}$ ,  $I_{\text{AS}}=80\text{A}$ ,  $R_G=25\Omega$ , Starting  $T_J=25^\circ\text{C}$ .
3. The data tested by pulsed, pulse width  $\leq 300\text{us}$ , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.



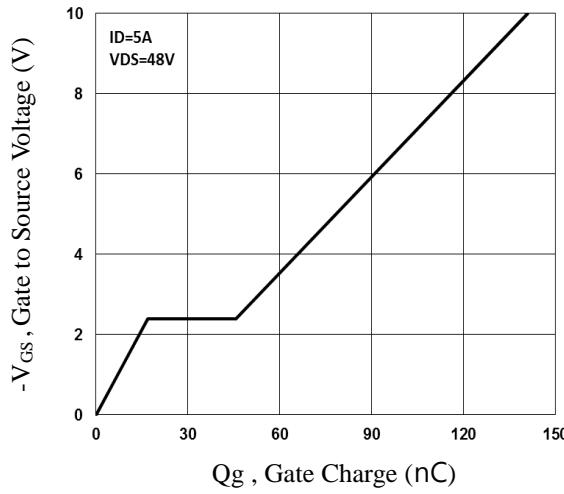
**Fig.1 Continuous Drain Current vs.  $T_c$**



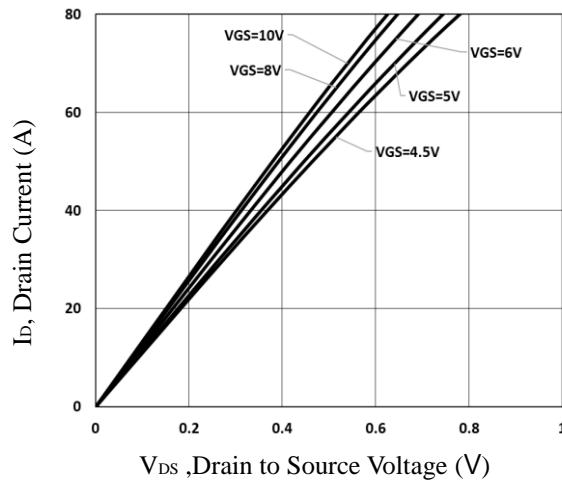
**Fig.2 Normalized  $R_{DS(on)}$  vs.  $T_J$**



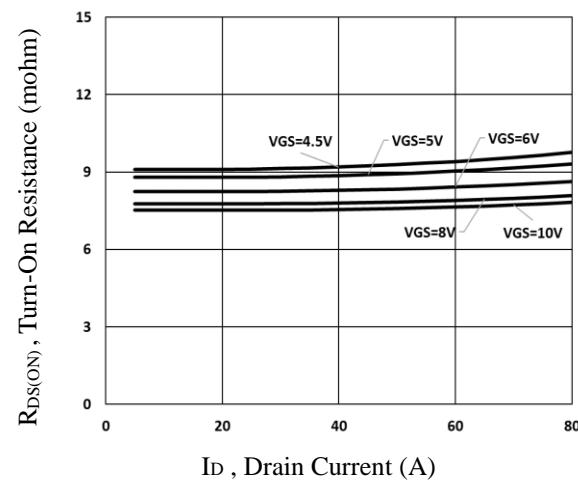
**Fig.3 Normalized  $V_{th}$  vs.  $T_J$**



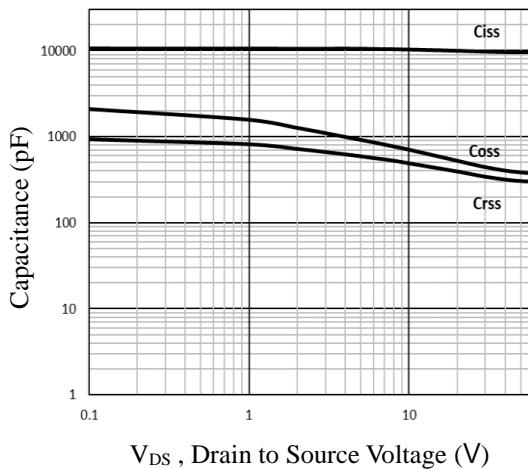
**Fig.4 Gate Charge Waveform**



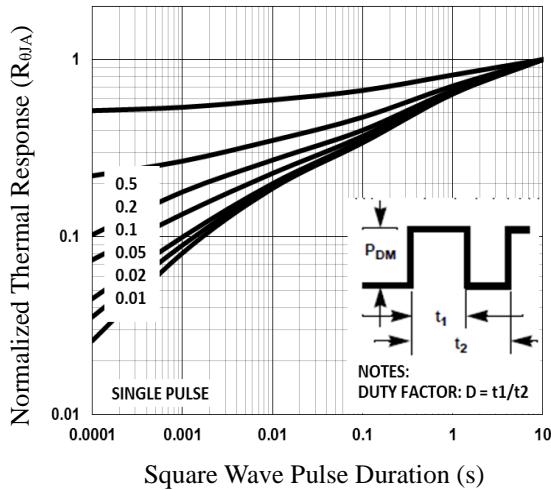
**Fig.5 Typical Output Characteristics**



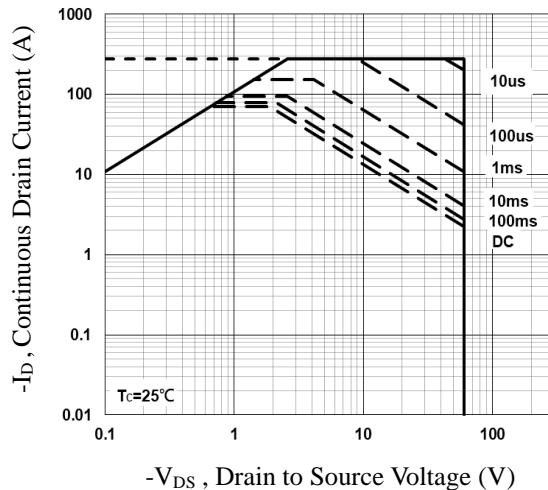
**Fig.6 Turn-On Resistance vs.  $I_D$**



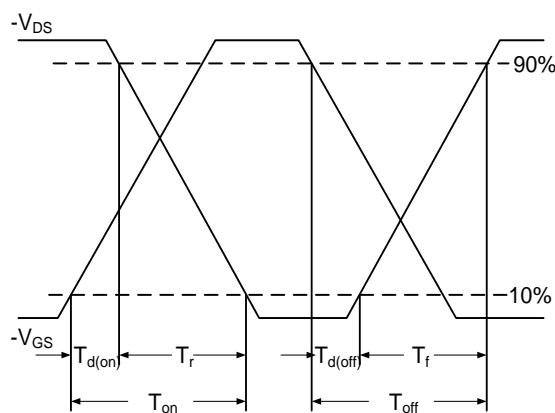
**Fig.7 Capacitance Characteristics**



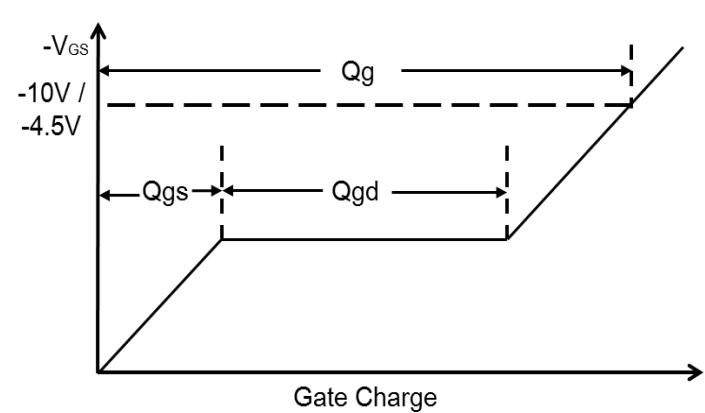
**Fig.8 Normalized Transient Impedance**



**Fig.9 Maximum Safe Operation Area**



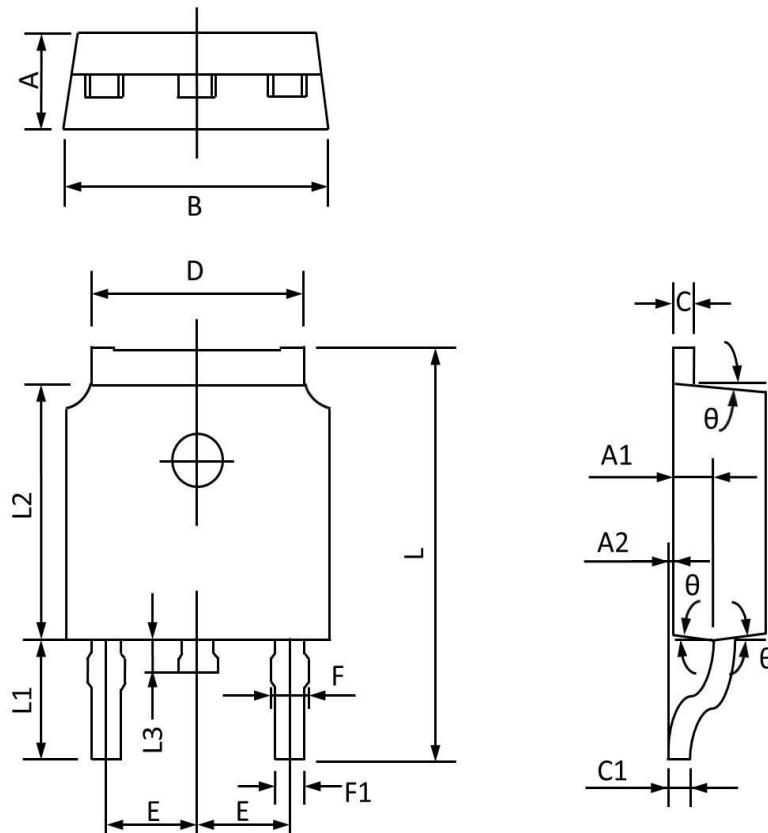
**Fig.10 Switching Time Waveform**



**Fig.11 Gate Charge Waveform**



## TO252 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	2.400	2.200	0.094	0.087
A1	1.110	0.910	0.044	0.036
A2	0.150	0.000	0.006	0.000
B	6.800	6.400	0.268	0.252
C	0.580	0.450	0.023	0.018
C1	0.580	0.460	0.023	0.018
D	5.500	5.100	0.217	0.201
E	2.386	2.186	0.094	0.086
F	0.940	0.600	0.037	0.024
F1	0.860	0.500	0.034	0.020
L	10.400	9.400	0.409	0.370
L1	3.000	2.400	0.118	0.094
L2	6.200	5.400	0.244	0.213
L3	1.200	0.600	0.047	0.024
θ	9°	3°	9°	3°